

MSC 4604 LSI-11 DUAL-HIGH MEMORY SYSTEM

M4604

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SECTION 1

INTRODUCTION

1.1 SCOPE

This manual provides information that the user needs to understand and maintain the MSC 4606 — a semiconductor memory system that fulfills LSI-11 bus protocol.

1.2 UNIT DESCRIPTION

The MSC 4604 is a single-board, dual-high memory system that is compatible with the LSI-11 Q-BUS*. Organization of the MSC 4604 is based on a 16K X 1 NMOS dynamic RAM. These elements mount on a 8.5- by 5.2-inch printed-circuit board along with the necessary interface components to configure up to 589,824 bits of storage capacity on one board.

Voltage normally present on the LSI-11 backplane supply the power required by the MSC 4604. An on-board DC-to-DC converter uses +12V line to generate the -5V substrate bias for the NMOS storage elements.

1.3 CONFIGURATION

Four major configurations of the MSC 4604 are available. They are: (1) 16K X 16, (2) 32K X 16, (3) 16K X 18, and (4) 32K X 18. Modular addressing is switch selectable. The starting address can be set to any 1K boundaries from 0 to 128K. Furthermore, the board capacity is on 1K boundaries so that the user can use 1K, 2K or 3K of the I/O page for main memory.

*LSI-11 and Q-Bus are Digital Equipment Corp. Trademarks.

1.3.1 Battery Back Up

Uninterruptable voltage sources may be connected to the MSC 4604 via the Q-BUS, which will power only the array and refresh logic. In this mode, non-volitility can be maintained during power failures and/or extended power down. This option is jumper selectable on the MSC 4604.

1.3.2 Refresh

The MSC 4604 has the capability to perform three modes of refresh operation. These switch selectable options include internal distributed refresh, and external refresh with or without the generation of the reply signal that is asserted to the bus master.

SECTION 2

SPECIFICATIONS

2.1 SCOPE

This section presents specifications and capabilities of the MSC 4604.

2.2 SPECIFICATIONS

2.2.1 Access/Cycle Time

Access (nanoseconds):

(Typical	Maximum
Read (DATI)	240	255
Write (DATO)	240	255
Read-Modify-Write	665	685
Cycle (nanoseconds):	Typical	Maximum
Q-BUS Refresh (including arbritration)	SYNC H + 20 540	SYNC H + 32 580

Assumptions: SYNC H to DIN H - 25 nanoseconds SYNC H to DOUT H - 50 nanoseconds RPLY H to DOUT H - 350 nanoseconds

2.2.2 Power Requirements

DC Requirements: LSI-11 backplane supplies require DC voltages See Table 2-1 for power requirements of each configuration.

ORGANIZATION	BATTERY	SUPPLY		ATING ENT(A)	STAND CURRE		POWEI DOWN CURRI	
	BACKUP	VOLTAGE	Typ.	Max.	Тур.	Max.	Typ.	Max.
		+5V	0.54	0.80	0.46	0.68	-	-
32K X 18	YES	+5VB	0.76	1.10	0.72	1.05	0.76	1.10
		+12VB	0.34	0.48	0.06	0.10	0.12	0.17
		+5V	4.54	0.80	0.40	0.68	_	_
16K X 18	YES	+5VB	0.76	1.10	0.72	1.05	0.76	1.10
		+12VB	0.25	0.40	0.04	0.08	0.07	0.11
		+5V	0.54	0.80	0.46	0.68	_	-
32K X 16	YES	+5VB	0.76	1.10	0.72	1.05	0.76	1.10
		+12VB	0.34	0.48	0.06	0.10	0.12	0.17
		+5V	0.54	0.80	0.46	0.68	-	-
16K X 16	YES	+5VB	0.76	1.10	0.72	1.05	0.76	1.10
		12VB	0.25	0.40	0.04	0.08	0.12	0.11
32K X 18	NO	+5V	1.30	1.90	1.18	1.73	-	-
		+12V	0.34	0.48	0.06	0.10	-	1000
16K X 18	NO	+5V	1.30	0.90	1.73	1.73	_	-
		+12V	0.25	0.40	0.04	0.08	-	-
32K X 16	NO	+5V	1.30	1.90	1.18	1.73	_	-
		+12V	0.34	0.48	0.06	0.10	-	-
16K X 16	NO	+5V	1.30	0.90	1.73	1.73	-	-
	•	+12V	0.25	0.40	0.04	0.08	_	-

Table 2-1
MSC 4604 POWER REQUIREMENTS

2.2.3 Bus Signals

All logic levels to and from the bus are TTL compatible. All Q-BUS timing conforms to LSI-11 protocol. I/O pin assignments of the MSC 4604 are listed in Table 2-2.

	,			
BUS	A CON	NECTOR	в со	NNECTOR
PIN	SIDE 1	SIDE 2	SIDE 1	SIDE 2
A	-	+5V	BDCOK H	+5V
В		-	-	-
С	BDAL16L	GND	-	GND
D	BDAL17L	+12V	-	+12V
E	-	BDOUTL	-	BDAL02L
F		BRPLYL	-	BDAL03L
H	-	BDINL	-	BDAL04L
J	GND	BSYNL	GND	BDAL05L
K	REFKILL	BWTBTL	-	BDAL06L
L	-	-	-	BDAL07L
M	GND	BIAKIL	GND	BDAL08L
N	-	BIAKOL	-	BDAL09L
P	-		-	BDAL10L
R	BREFL	BDMGIL	-	BDAL11L
S	+12B	BDMGOL	-	BDAL12L
T	GND	-	GND	BDAL13L
U	-	BDALOOL		BDAL14L
V	+5V	BDAL01L	+5V	BDAL15L

Table 2-2 MSC 4604 I/O CONFIGURATION

2.2.4 Bus Load

AC Load: The MSC 4604 presents two AC loads to the bus (18.7 pF of capacitance maximum).

DC Load: The MSC 4604 presents one DC load to the bus (105 microamperes of leakage current nominal)

2.2.5 Operating Environments

Operating Temperature: 0° C to +50° C
Storage Temperature: -40° C to +66° C
Relative Humidity: up to 90% without condensation

2.2.6 Physical Dimensions

Mounted on a glass-epoxy, printed-circuit board with the following dimensions:

Height: 5.2 in. (13.2 cm). Length: 8.5 in. (21.6 cm).

Non-conductive component height limit: 0.375 in. (0.97 cm) max.

2.3 CAPABILITIES

2.3.1 Address Channel

The MSC 4604 accepts 18 bits of address information that locates a unique data word. Address bits BDALO1 L thru BDAL17 L select the memory location, and BDAL00 L denotes the byte. The incoming address is latched into an address register upon the initiation of BSYNC L.

2.3.1.1 Address Programming

On-board DIP switches allow the user to quickly change the starting address and storage capacity of the MSC 4604 in IK increments. The incoming address lines are compared with the programmed switch settings. In event the address is within the programmed limits, the designated memory operation is then initiated.

2.3.2 Data Channel

Data is transferred to, or received from, the bus master on Q-BUS lines BDALOO L thru BDAL15 L during the DIN or DOUT portions of the bus cycle.

2.3.3 LSI-11 Bus Interface

The MSC 4604 meets Digital Equipment Corporation specifications protocol for the LSI-11 Bus. Two signals achieve synchronization between the processor and the MSC 4604 -- BSYNC L (Bus Sync) and BRPLY L (Bus Reply). The bus master asserts BSYNC L to initiate a cycle and indicate that address information is present on the bus. The master then asserts BDIN L for a read or BDOUT L for a write operation. The MSC 4604 acknowledges with BRPLY L to indicate to the master that either data is available (read command) or data has been accepted from the bus (write command) respectively.

2.3.3.1 Data Transfer Cycles

When data is read out of an addressed memory location, this is called a DATI bus cycle. If data is transferred from the bus to the addressed location, this is a DATO cycle or write operation. In addition, DATIO cycles indicate an output transfer succeeding an input transfer. This cycle provides an efficient means of executing a read-modify-write operation by making it unnecessary to assert an address a second time (IN and OUT designations are bus master references).

2.3.3.2 DATIO Cycle

A DATIO cycle is equivalent to a read-modify-write operation. An addressing operation and an input word transfer are first executed as described in paragraphs 4.3.2 (DATI). However, BSYNC L remains in an active state after the input data transfer is complete. This causes the MSC 4604 to remain selected, and an output data transfer follows without further addressing. After completing the output data transfer operation, the DATIO cycle is complete when BSYNC L is unasserted.

2.3.3.3 Refresh

Refresh of the dynamic storage cell requires that each of the row addresses be asserted within two milliseconds. This requires a minimum of 128 refresh cycles every two milliseconds. When neither a write nor read operation is in progress, a refresh cycle may be initiated. If a read or write is asserted on the bus during a refresh cycle, the Q-BUS information is stored until the refresh cycle is complete.

The MSC 4604 controls all refresh functions and timing as required for internal distributed refresh. For external refresh, the bus master asserts BREF L during the address portion of each refresh cycle for each BSYNC/BDIN operation. BREF L allows all dynamic memory elements of the MSC 4604 to be enabled and addressed simultaneously.

During external refresh operation, only the slowest device being refreshed should generate a reply. Whether or not the MSC 4604 responds with BRPLY L is switch selectable.

2.3.4 Timing And Control

Delay-line circuitry establishes the internal timing as required for proper operation of the MSC 4604. For external control, the MSC 4604 accepts LSI-ll bus signals. Table 2-3 lists and describes these signals.

MNEMONIC	DESCRIPTION	FUNCTION
BDALO L-BDAL17 L	Data Address Bits	Transfer Address and data information between the MSC 4604 and the bus master. The bus master asserts the address data on the bus first, and then the MSC 4604 either receives or sends the data word on the same lines.
BSYNC L	Bus Sync	Generate by the bus master to initiate a cycle and indicate that the address is on BDALO L thru BDAL17 L. The requested transfer remains in process until SYNC L is negated.
BDIN L	Data In	Involved with two bus operations. When asserted by the bus master during BSYNC L, the master device is ready to accept data from the MSC 4604. An interrupt operation is indicated when BDIL L is asserted with out BSYNC L.
BDOUT L	Data Output	Implies valid data is available on the bus and that an output transfer with respect to the bus master, is taking place. The MSC 4604 responds to BDOUT L with BRPLY L to complete the transfer.
BRPLY L	Reply	Is asserted by the MSC 4604 in response to either BDOUT L or BDIN L.

Table 2-3
BUS CONTROL SIGNALS.

MNEMONIC	DESCRIPTION	FUNCTION
BWTBT L	Write/Byte	Controls the MSC 4604 two ways. If asserted during the leading edge of BSYNC L, an output sequence (DATO or DATOB) will follow. If unasserted during the leading adge of BSYNC L, a DATI or DATIO cycle will follow. BWTBT L is also asserted during BDOUT L in a DATOB bus cycle to indicate byte addressing.
BREF L	Memory Refresh	When asserted by a bus master, activates all NMOS memory elements for each BSYNC L/BDIN I transaction.
REFKIL L	Refresh Control	Inhibits internal refresh

Table 2-3(cont.)
BUS CONTROL SIGNALS

SECTION 3

INSTALLATION

3.1 SCOPE

This section gives recommended procedures for properly installing the MSC 4604.

3.2 UNPACKING AND INSPECTION

Carefully remove the memory system from the shipping container and packing material from the assembly. Inspect the board for damage or loose connections and components.

3.3 INSTALLATION

After the initial inspection, use the step-by-step procedure that is outlined in the following paragraphs for system installation.

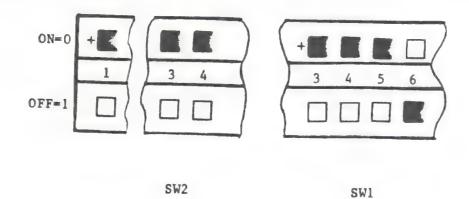
1) Set up the on-board DIP switches SWl and SW2 using Table 3-1 (starting address) and 3-2 (capacity). The following example demonstrates how to program these switches.

EXAMPLE 3-1: PROGRAMMING THE ADDRESS SWITCHES

For a 32K system with a starting address of 8K, the switch settings are determined in the following manner:

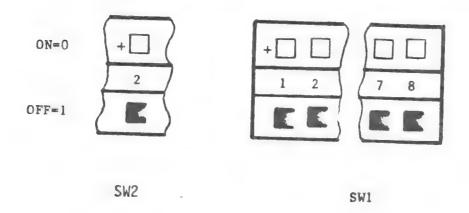
A. STARTING ADDRESS

Using Table 3-1, 8K setting of SWl and SW2 is illustrated in the following diagram (shaded area indicates the switch is depressed to that side).



B. CAPACITY

The following diagram illustrates the DIP switch setting for 32K capacity using Table 3-2 (shaded area indicates the switch is depressed to that side).



c	TARTING		SWI	TCH	SET	TIN	G					SWI	TCH	SET	TIN	G	
	DDRESS		SW2			S	W1		_	TARTING DDRESS		SW2			S	W1	
K	OCTAL	3	4	1	6	3	4	5	K	OCTAL	3	4	1	6	3	4	5
0	000000	0	0	0	0	0	0	0	32	200000	0	1	0	0	0	0	0
1	004000	0	0	0	0	0	0	1	33	204000	0	1	0	0	0	0	1
2	010000	0	0	0	0	0	1	0	34	210000	0	1	0	0	0	1	0
3	014000	0	0	0	0	0	1	1	35	214000	0	1	0	0	0	1	1
4	020000	0	0	0	0	1	0	0	36	220000	0	1	0	0	1	0	0
5	024000	0	0	0	0	1	0	1	37	224000	0	1	0	0	1	0	1
6	030000	0	0	0	0	1	1	0	38	230000	0	1	0	0	1	1	0
7	034000	0	0	0	0	1	1	1	39 234000 40 240000 41 244000 42 250000 43 254000		0	1	0	0	1	1	1
8	040000	0	0	0	1	0	0				0 40 240000	1	0	1	0	0	0
9	044000	0	0	0	1	0	0	1				0	1	0	1	0	0
10	050000	0	0	0	1	0	1	0				1	0	1	0		
11		0	0	0	1	0	1	1 43 254000			0	1	0	1	0	1	1
12	060000	0	0	0	1	1	0 0 44 260			0	1	0	1	1	0	0	
13	. 064000	0	0	0	1	1	0	1	45 264000		0	1	0	1	1	0	1
14	070000	0	0	0	1	1	1	0	46	270000	0	1	0	1	1	1	0
15	074000	0	0	0	1	1	1	1	47 274000		0	1	0	1	1	1	1
16	100000	0	0	1	0	0	0	0	48	300000	0	1	1	0	0	0	0
17	104000	0	0	1	0	0	0	1	49	304000	0	1	1	0	0	0	1
18	110000	0	0	1	0	0	1	0	50	310000	0	1	1	0	0	1	0
19	114000	0	0	1	0	0	1	1	51	314000	0	1	1	0	0	1	1
20	120000	0	0	1	0	1	0	0	52 320000 53 324000 54 330000 55 334000		0	1	1	0	1	0	0
21	124000	0	0	1	0	1	0	1			0	1	1	0	1	0	1
22	130000	0	0	1	0	1	1	0			0	1	1	0	1	1	0
23	134000	0	0	1	0	1	1	1			0	1	1	0	1	1	1
24	140000	0	0	1	1	0	0	0	56	340000	0	1	1	1	0	0	0
25	144000	0	0	1	1	0	0	1	57	344000	0	1	1	1	0	0	1
26	150000	0	0	1	1	0	1	0	58	350000	0	1	1	1	0	1	0
27	154000	0	0	1	1	0	1	1	59	354000	0	1	1	1	0	1	1
28	160000	0	0	1	1	1	0	0	60	360000	0	1	1	1	1	0	0
29	164000	0	0	1	1	1	0	1	61	364000	0	1	1	1	1	0	1
30	170000	0	0	1	1	1	1	0	62	370000	0	1	1	1	1	1	0
31	174000	0	0	1	1	1	1	1	63	374000	0	1	1	1	1	1	1

(0=0N, 1=0FF)

Table 3-1 STARTING ADDRESS SWITCH SETTINGS

	STARTING		SWI	тсн	SE1	TIN	IG					SWI	тсн	SET	TIN	IG	
	DDRESS		SW2	2		S	W1			ARTING DRESS		SW2	2		S	Wl	
K	OCTAL	3	4	1	6	3	4	5	K	OCTAL	3	4	1	6	3	4	5
64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 80 81 82 83 84 85 86 87 88 89 90 91	400000 404000 410000 414000 420000 424000 434000 444000 454000 454000 464000 474000 500000 514000 514000 514000 520000 514000 524000 534000 544000 554000 554000			0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	0 0 0 0 0 0 0 0 0 0 0 0 1 1 1 1 1 1 1 0	0 0 0 0 0 0 1 1 1 1 0 0 0 0 0 1 1 1 1 0	0 0 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 0 0 0 1 1 0 0 0 1 1	0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1	96 97 98 100 101 102 103 104 105 106 107 108 109 110 111 112 113 114 115 116 117 118 119 120 121 122 123 124	600000 604000 610000 614000 620000 624000 630000 644000 654000 654000 664000 674000 710000 714000 720000 724000 730000 734000 744000 750000 754000			0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0		0 0 0 0 0 1 1 1 1 0 0 0 0 0 1 1 1 1 0 0 0 0 0 1 1 1 1 0	0 0 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 0 0 0 1 1 0 0 0 1 1	0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1 0 1
92 93 94 95	560000 564000 570000 574000	1 1 1 1	0 0 0	1 1 1 1 1	1 1 1 1	1 1 1 1 1	0 0 1 1 1	0 1 0	125 126 127 128	760000 764000 770000 774000	1 1 1 1	1 1 1 1	1 1 1 1 1	1 1 1 1	1 1 1 1 1	0 0 1 1	0 1 0 1

(0=0N, 1=0FF)

Table 3-1 (cont.)
STARTING ADDRESS SWITCH SETTINGS

MEMORY SIZE	SV	VITCH SETTINGS
(K)	SW2	SWl
	2	8 1 2 7
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27	0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 1 1 1 1 1	0 0 0 0 0 0 0 0 0 0 0 1 0 0 1 1 1 1 1 1
28 29 30 31 32	1 1 1 1 1	1 0 1 1 1 1 0 0 1 1 0 1 1 1 1 0

(0=0N, 1=0FF)

Table 3-2 SWITCH SETTING FOR CAPACITY

SECTION 4

THEORY OF OPERATION

4.1 SCOPE

This section details the theory of operation that is necessary to understand and maintain the MSC 4604.

4.2 SYSTEM INTERFACE

The MSC 4604 interfaces with the LSI-11 bus via standard DEC block. For signal and pin identification, see Table 2-2.

4.3 SYSTEM DESCRIPTION

The MSC 4604 performs either a read or write operation using the LSI-11 bus signals listed in Table 2-2.

4.3.1 Address

The MSC 4604 processes the 16-bit address on input lines BDALO thru BDAL15 in the following manner:

- 1) When the bus master places the address on BDALO L thru BDAL15 L and asserts BSYNC L, the MSC 4604 determines if the memory is to be accessed. These address lines, routed through the bus receivers are compared with the setting of on-board DIP switches. The procedure for setting up these switches is outlined in paragraph 3.3.
- 2) If it is established on the leading edge of BYSNC L that the MSC 4604 is accessible, the address field is latched and decoded to select a unique memory location. Also, the requested memory operation as defined by either BDIN L or BDOUT L is initiated. Whenever the requested bus cycle is DATOB, signal BDALOO L defines the byte that is to be modified during the write operation.

4.3.2 Read (DATI)

The DATI cycle transfers data from the MSC 4604 to the LSI-11 bus. If a DATI cycle is requested, the MSC 4604 responds in the following manner:

 The bus master asserts the address information on BDAL00 L thru BDAL15 L. After 150 nanoseconds, the bus master then asserts BYSNC L.

- The MSC 4604 accepts the address information. Upon receipt of BYSNC L, the address is then latched and decoded if the address presented is within the programmed limits.
- 3) The bus master removes the address from BDAL00 L thru BDAL15 L and asserts BDIN L.
- 4) When the data read from the addressed location becomes stable, this information is then asserted onto the bus. To indicate that data is now available, the MSC 4604 sends BRPLY L to the bus master. If BRPLY L is not asserted within 10 microseconds (maximum) after BDIN L is asserted, the bus master terminates the cycle and goes into a trap routine (Timeout).
- 5) The bus master clears BDIN L to acknowledge receipt of the data. In turn, the MSC 4604 negates BRPLY L. The cycle is complete when the bus master clears BSYNC L. The system is now ready for another transaction.

4.3.3 Write (DATO or DATOB)

Both DATO and DATOB involve data transfers from the bus master to the MSC 4604. The only difference is that DATO signifies a word transfer and DATOB is a byte transfer. The following functions are performed during the write cycle:

- 1) The bus master asserts the address information BDAL00 L thru BDAL15 L and BWTBT L. After 150 nanoseconds, the bus master then asserts BSYNC L.
- 2) The MSC 4604 accepts the address, and then compares the address information with the programmed address limits. If the address data is valid, the board is enabled upon receipt of BSYNC L.
- 3) The bus master removes the address from BDAL00 L thru BDAL15 L and negates BWTBT L. Following a short time delay, the data word is placed on the bus (BDAL00 L thru BDAL15 L). In turn, BDOUT L is asserted to signify that valid data is now available on the bus.
- 4) The MSC 4604 accepts the information on the data line BDAL00 L thru BDAL15 L. In response to the BDOUT L signal, the MSC 4604 asserts BRPLY L to complete the transfer. If BRPLY L is not asserted within 10 microseconds, the bus master terminates the cycle (Timeout).
- 5) The bus master responds to BRPLY L by clearing BDOUT L, and BWTBT L if the requested transfer cycle is DATOB.
- 6) The MSC 4604 negates BRPLY L to release the bus for another transaction while completing internal write functions. In turn, the bus master clears BYSNC L to finish the cycle and prepare for the next operation.

4.4.1 Memory Addressing

Transceivers accept the address word on bus input lines BDAL00 L thru BDAL17 L, and convert them to internal signals A00 thru A17. Adders U2 and U12 assign the starting address for the MSC 4604 as "ADDRESS 0", based on the settings of SWI and SW2, and the summation outputs of U2 and U12 to establish the storage capacity. The carry output or pin 14 of U3 remains "high" as long as the address word accepted from the bus is within the programmed limits of the MSC 4604. In turn, a "low" signifies that the programmed capacity has been exceeded and all requested memory operations will be inhibited (pin 4, U14).

4.4.2 Address Decoding

When the requested memory operation is initiated, the "low" that is asserted on BSYNC L loads the row address and column address in tri-state latches U6 and U5 respectively. Under control of EN RAS ADD L (row select) and EN CAS ADD L (column select), address bits A00 thru thru A06 (row address) are multiplexed with address bits A07 thru A15 (column address) to be used as required by the memory elements. Signal BSYNC L also latches address bits A15 thru A17 in U4.

4.4.2.1 Refresh Address

The outputs of tri-state driver U7 are multiplexed with row/column address bits A01 thru A15. When there is no memory operation in progress, pins 1 and 19 of U7 go "low", asserting the outputs of the Refresh counter U14 onto the row/column select lines. As the Refresh counter is incremented following each refresh cycle, the address applied to the memory elements changes accordingly.

4.4.3 Data Path

The MSC 4604 routes 16-bits of data (BDAL00 L thru BDAL15 L) to and from the bus for either a read or write operation via transceivers U8, 9, 30 and 32. If a write operation is requested, signal DOUT H (BDOUT L inverted) allows the data word to flow from the bus through U30 and U32. Under control of DIN L or DOUT L, transceivers U8 and U9 then convert BDAL00 L thru BDAL15 L to internal signals DI00 thru DI15. In turn, the resultant signals are applied to the selected memory array location and stored.

4.4.4 Timing And Control

The timing and control circuits perform two functions: (1) decode the command signals that are asserted on the bus, and (2) generate the control signals and timing sequence as required to perform the designated memory operation.

4.4.4.1 Read Command

For a read command, the "low" asserted on BSYNC L enables the condition of the carry line from adder U3 (See paragraph 4.4.1) in U35. If the address is within the programmed limits, a "high" is placed on pin 1 of U24. This signal in conjunction with SYN H (BYSNC L inverted) conditions flip-flop U35. In turn, this forces MEM CY H "high" (U35, pin 9), and a "low" is then placed on the input of the delay line U20 (DLA).

BDIN L causes EN and DLB (tap 1 of U27) to generate RPLY H (U20, pin 5) via gates U11 and U26. Drive U39 then asserts this signal as BRPLY L onto the bus. This timing operation allows the data word to read out of the memory and be placed onto the bus under control of DIR H.

4.4.4.2 Write Command

Generation of MEM CY H and the delay-line timing is the same as previously described in paragraph 4.4.4.1. However, DIN L remains "high" causing DIR H to remain "low", (U19, pin 6) and the bus transceivers to accept and transfer the data word from the Q-BUS onto the internal data bus DAO1 L In turn, the "low" on DIR H also allows EN CAS ADD L o transfer this data into the addressed location via U8 and U10.

Signal WTBT H with A00 L (BDAL00 L) designates byte or word operation. If WTBT H is "low", both pins 12 and 13 of U17 will be "high", applying a "low" on both WE or Write Enable lines (U9, pins 2 and 5) to the memory chips — causing the complete word to be written into memory. A "high" on WTBT H defines a write operation on byte basis (DATOB). Now pins 12 and 13 of U17 are conditioned (high) so that the state of A00 L controls which WE line will go "low" through the decoding gates of U17.

4.4.4.3 Internal Timing And Control

As the "low" and "high" levels shift through delay lines DLA (U26) and DLB (U27), the output taps are encoded to provide the timing pulses as required by both the memory elements and the MSC 4604. Each delay line has five delay taps with a 50-nanosecond delay between taps.

The normal quiescent state for DLA is "high" and for DLB is "low". The setting of U21 (MEM CY H) forces pin 12 of U35 "high". If a refresh cycle is not in progress (REF CY H). the "high" on input pin 12 of U35 applies a "low" on the input of DLA. This "low" then traverses through DLA. Signal DLA3 is applied to U35, pin 2 and U25, pin 1. Gate U35 (pins 1 thru 3) enables DOUT OR DIN H to set CAS EN H "high" (U21, pin 5). This "high" (CAS EN H) is asserted also on the input of DLB> Tap 1 of DLB generates BRPLY L which resets DIN OR DOUT H. This then sends a "low" a through DLB, and BRPLY L is reset. When BRPLY L goes "high", BSYNC L is then unasserted on the bus; EN MEM L (U14, pin 6) goes "high"; and latch U35 is reset, forcing MEM CY H "low". In turn, the inputs of DLA goes "high", which is shifted through the delay line U26.

4.4.4.4 Refresh Cycle

Refresh of the dynamic storage cell requires that each of the row addresses to be cycled within two-milliseconds. This requires a minimum of 128 cycles every two-milliseconds. Timer U24 controls this timing requirement. This timer is set up to generate a pulse width of 11- to 13-milliseconds on pin 4, allowing 128 cycles to be completed well within the two-millisecond requirement. Upon timing out, pin 4 of U24 goes "high", requesting a refresh cycle through U25, pins 11 thru 13.

If neither a read or write has been requested (pin 8 of U21 is "high"), the 100 nanosecond pulse on pin 12 of U24 sets the Refresh latch U40 (a "high" on pin 9), forcing REF CY H "high". This "high" indicates a refresh cycle has been initiated. The action of the Refresh latch inhibits CAS L circuits so that all chips are inhibited from performing a normal memory cycle. The Refresh counter U15 is incremented when a refresh cycle terminates. Encoding the signals from taps 3 and 4 of DLA generates RST REF H, which asserts a "low" on pin 13 of U40. This action forces pin 9 of U40 "low" and timer U24 is then retriggered. Upon timing out (pin 4 goes "low"), the 100 nanosecond pulse on pin 12 of U24 initiates a refresh cycle through the setting of the Refresh latch U40.

4.4.4.5 Refresh Kill

This signal provides a means for halting internal refresh cycles at a specific time. When REF KILL L is asserted, any refresh in progress is allowed to terminate, but succeeding cycles are disabled — terminating any further refresh cycles.

4.4.4.6 External Refresh

An external source may be used to initiate a refresh cycle through the assertion of bus signal BREF L. This signal may be asserted during the address time for a single-cycle refresh, or held "low" for burst (repeated) refresh cycles. Bus receiver U38 accepts and generates the internal signal REF H. This signal (REF H) clocks the Refresh latch U40, initiating the refresh cycle.

When RST REF H goes "high" (Refer to paragraph 4.4.4.4), Refresh latch U40 is reset. The resultant "low" on pin 9 of U40 clocks Refresh Latch 2 (U40, pin 3), forcing ST REF 2L (pin 6) "high". This action places a "high" on pin 10 of U24 and allows DLA1 to trigger U24, pin 12. After 100 nanoseconds, U24 times out and the signal change on pin 12 clocks the Refresh latch, starting a second refresh cycle.

An open condition of SW3 (pins 4 and 6) disables RPLY H to allow the slowest device on the bus to send a reply. When the switch SW3 is closed, the MSC 4604 asserts BRPLY L onto the Q-BUS.

4.4.4.7 Parity

The MSC 4604 can check parity bits on a byte basis, expanding the data word from 16 to 18 bits -- one parity bit per byte. During a memory operation, parity circuits U16 (Byte 1) and U8 (Byte 0) checks the data word for correct parity. A "low" signal on BDAL16 L during the assertion of BRPLY L on the Q-BUS signifies a parity error.

SECTION 5

PREVENTIVE MAINTENANCE/TROUBLESHOOTING

5.1 SCOPE

This section describes the procedure that is recommended for troubleshooting the MSC 4604. The procedures that are outlined in this section are based on the fact that the user understands the normal operation of the MSC 4604 as described in the previous sections of this manual.

5.2 MAINTENANCE

Due to the solid-state nature of this memory system, maintenance requirements are minimum. However, running a memory diagnostic periodically guarentees memory integrity.

5.3 TROUBLESHOOTING

If a diagnostic or some other test indicates that the memory board is defective, check all voltages first. Then verify the presence of all bus signals.

Address lines should be confirmed in conjunction with the data input signals. If the board is functional except for a bit error at a specific address, then the defective element may be located using Drawing 305-0225-000 with Section 4 as a reference. If the board is determined to be defective, and a faulty element cannot be located or replaced, call the factory.

SECTION 6

WARRANTY

6.1 SCOPE

Monolithic Systems Corporation (MSC) warrants for a period of twelve (12) months from the data of shipment that each item of equipment (except those materials supplied by Buyer) shall be free from defects in material and workmanship under normal use and service. Any equipment which is not as warranted may be returned to Monolithic Systems Corporation at MSC's risk and expense for repair or replacement.

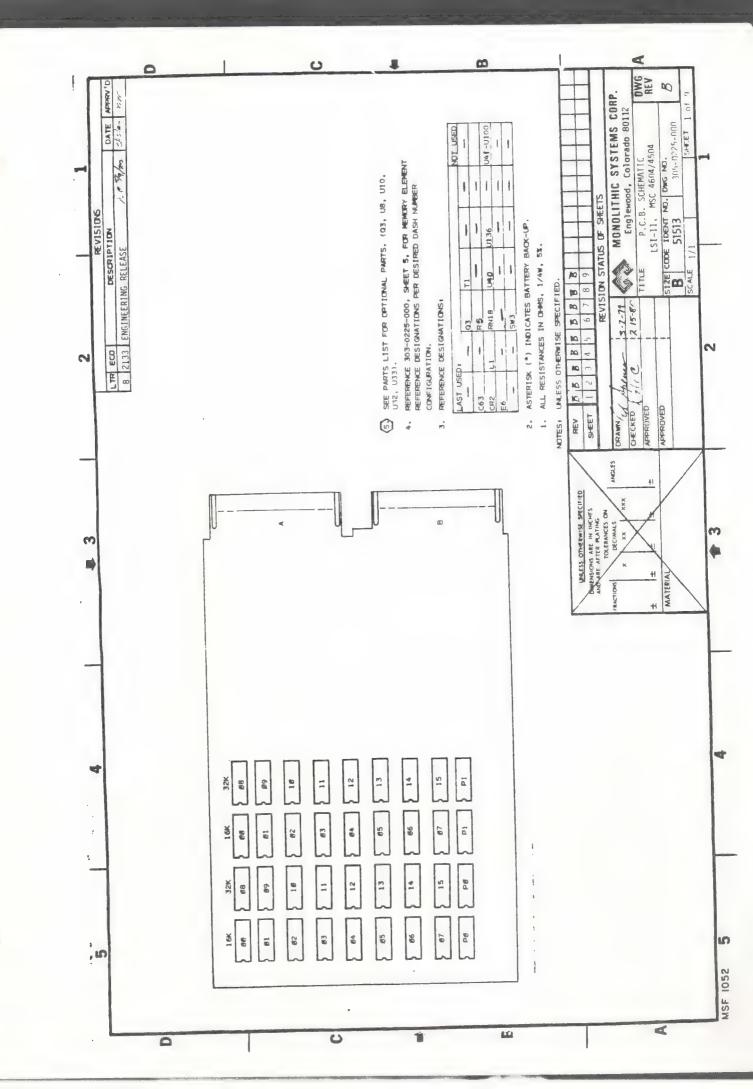
If the Buyer establishes that anyone of the items of equipment is not as warranted above in order to benefit from the warranty, the Buyer shall advise Monolithic Systems Corporation in writing during the warranty period describing in detail the defect claimed. Monolithic Sytems Corporation shall thereafter be afforded the opportunity, for a reasonable period of time after the defective equipment is returned to Monolithic Systems Corporation place of manufacture, to modify, adjust or repair such item of equipment in order to render it in conformity with the above warranty. If at the end of such period, the Buyer establishes that such item of equipment is still not in conformity with the above warrant then Monolithic Systems Corporation shall replace the defective item of equipment to the Buyer. The Buyer recognizes that the remedy of refund of the purchase price in the case of the breach by Monolithic Systems Corporation of the above warranty constitutes the sole and exclusive remedy to the Buyer for such breach. Equipment may consist of whole or in part, of refurbished components which are warranted equivalent to new when used for the purposes intended.

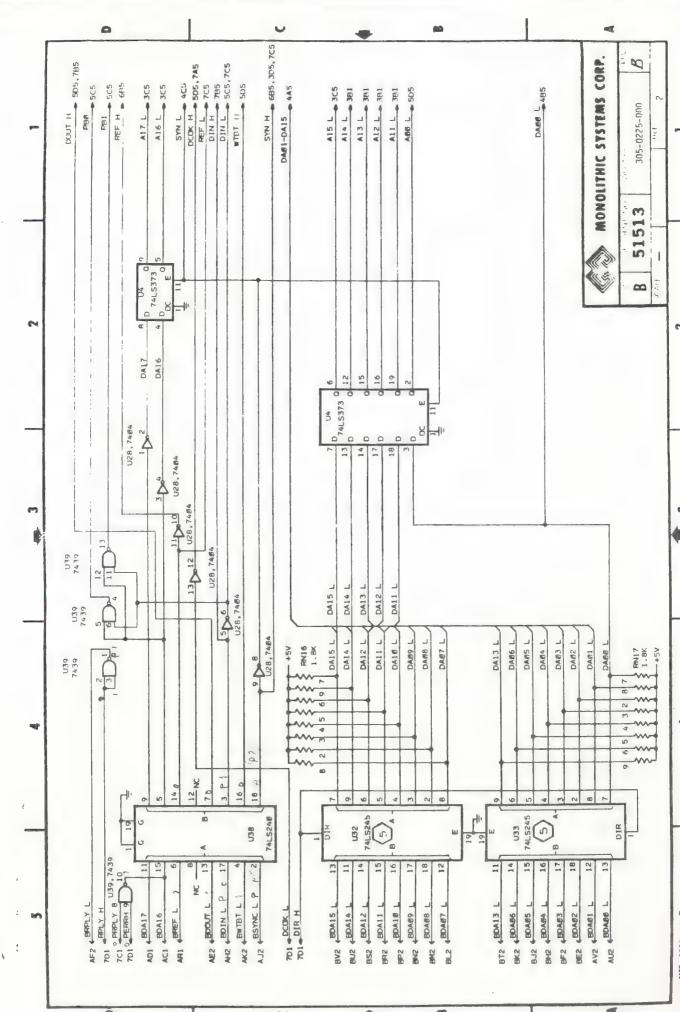
This warranty shall immediately terminate if the equipment is subjected to misuse, neglect, accident, damage in transit, transported in other than Monolithic Systems Corporation authorized containers, or is altered, repaired or overhauled by any person other than Monolithic Systems Corporation.

THE FOREGOING WARRANTY IS IN LIEU OF ALL OTHER WARRANTIES, PROMISES, AFFIRMATIONS OR REPRESENTATIONS, WHATSOEVER, EXPRESS OR IMPLIED, INCLUDING, BUT NOT LIMITED TO, ANY IMPLIED WARRANTY OF MERCHANTABILITY OR IMPLIED WARRANTY OF FITNESS OF EQUIPMENT FOR A PARTICULAR PURPOSE, AND OF ANY OTHER OBLIGATIONS ON THE PART OF THE SELLER.

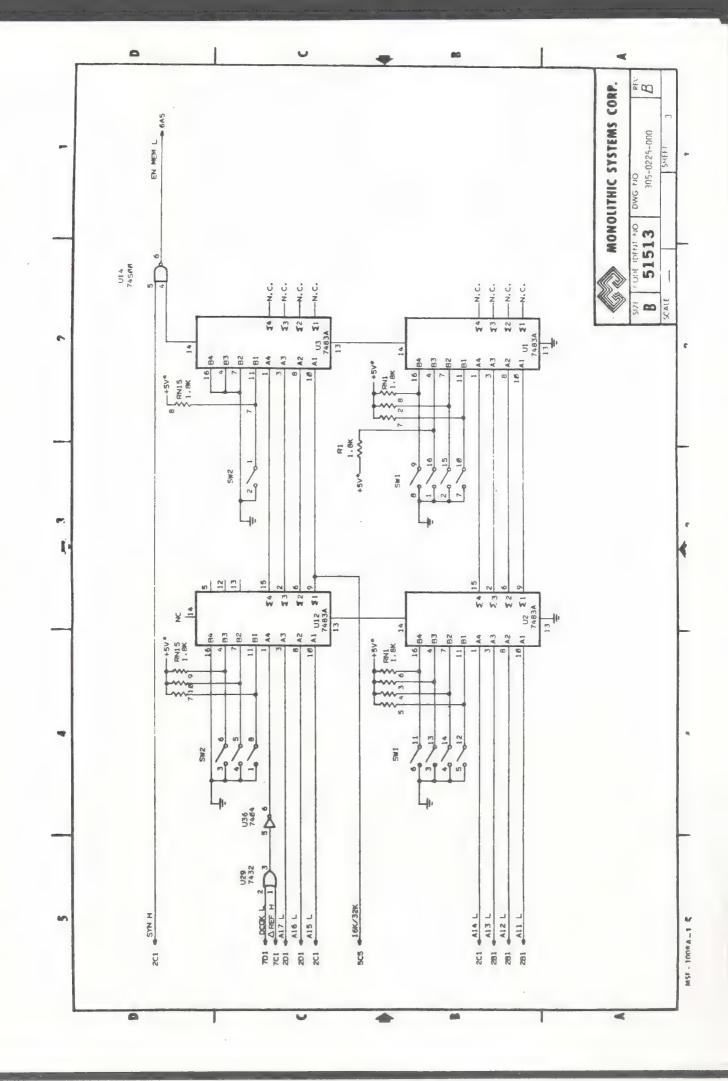
6.2 WARRANTY REGISTRATION

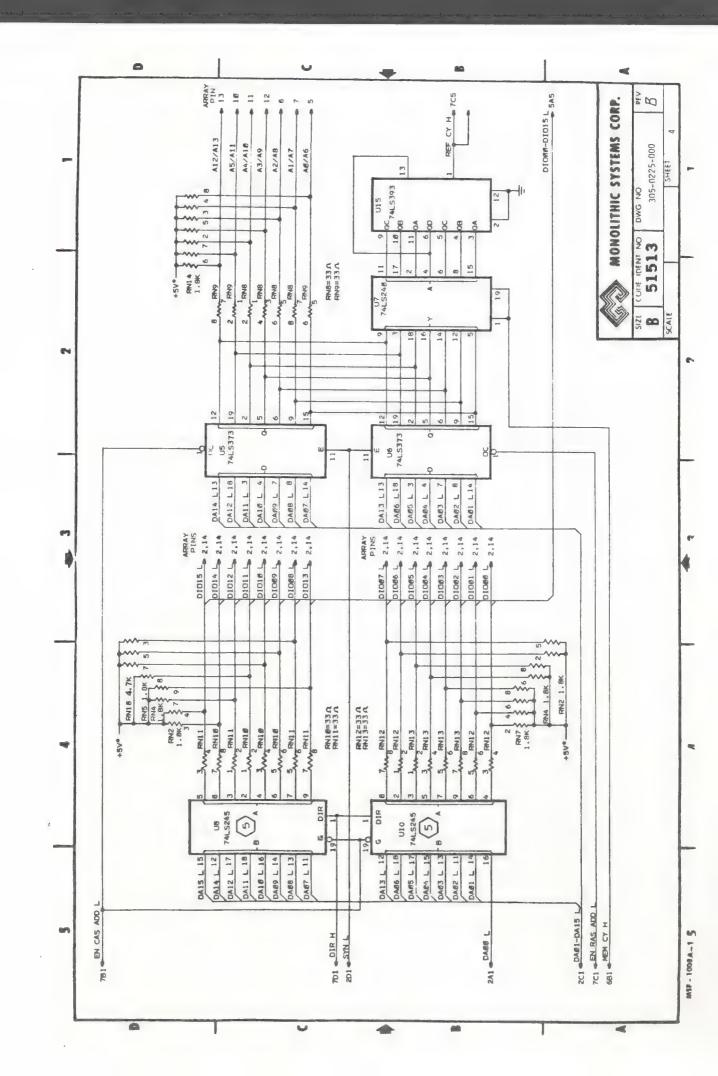
To expedite our warranty service, please fill out the WARRANTY REGISTRATION card at the front of this manual, and return to Monolithic Systems Corporation.

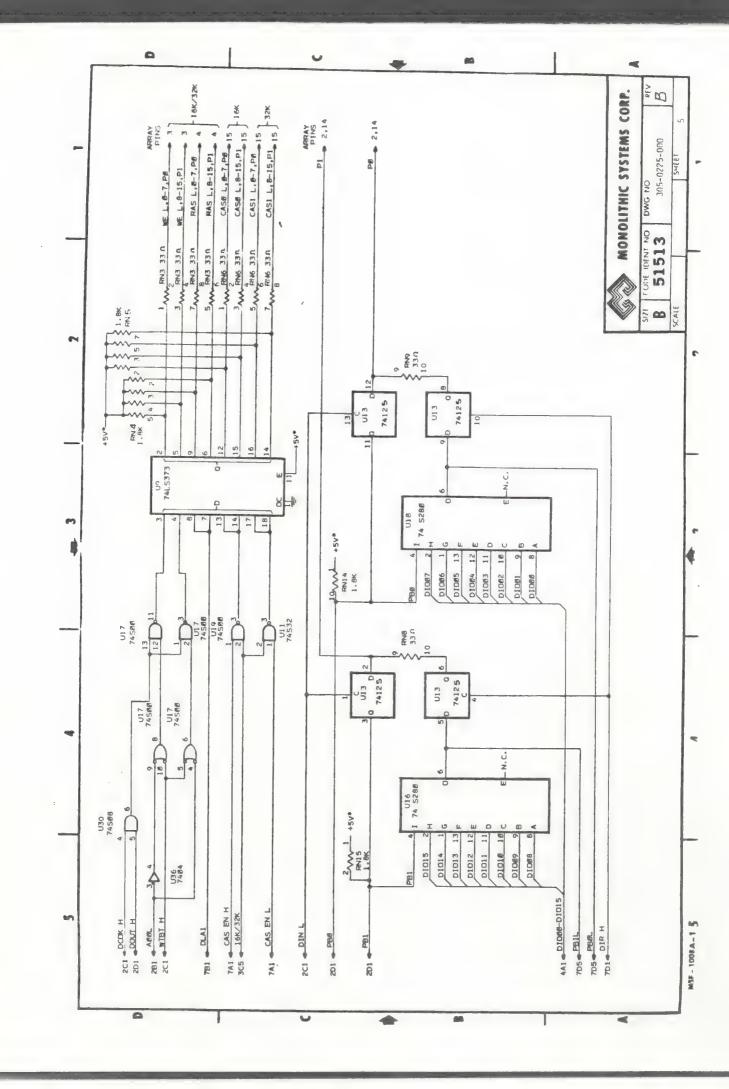


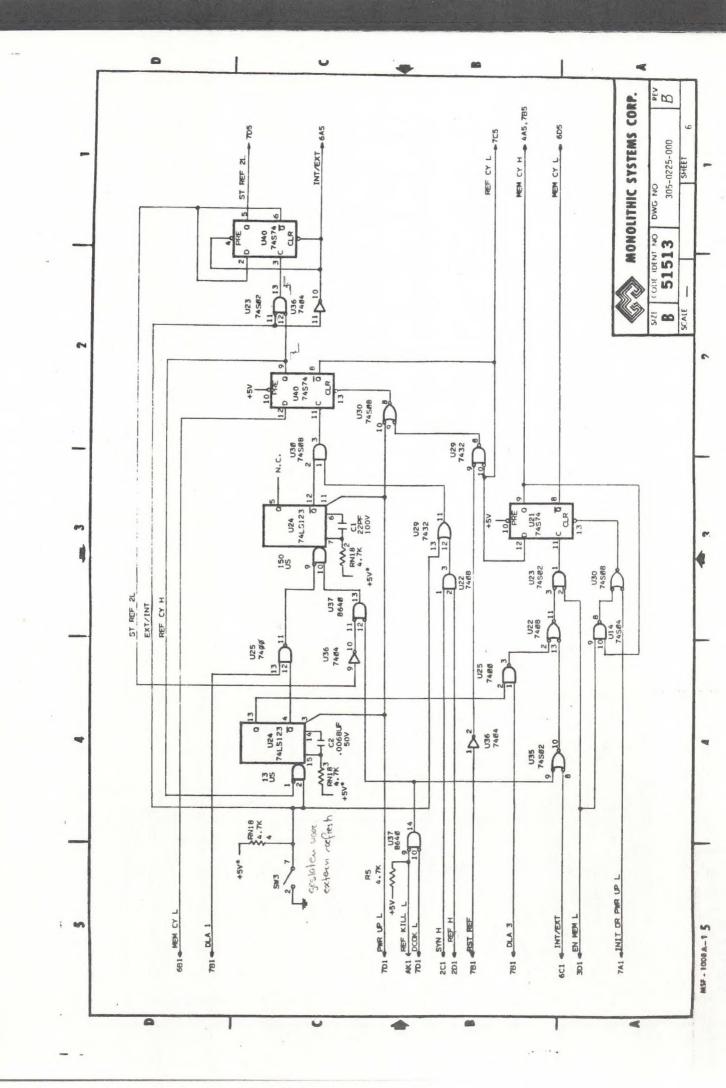


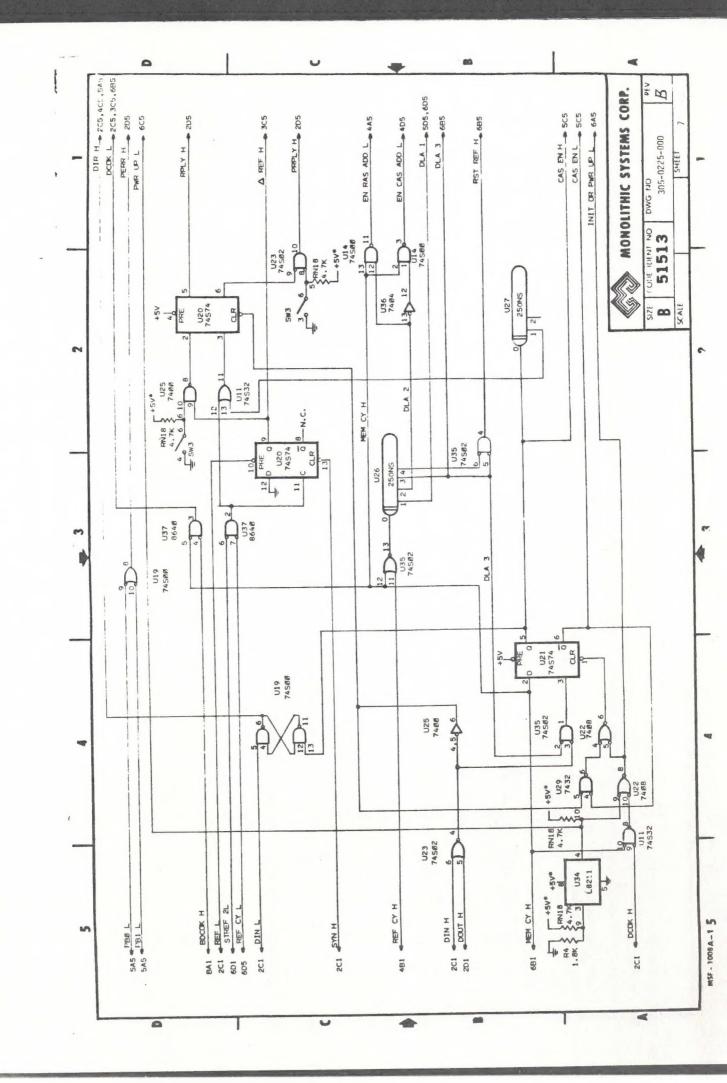
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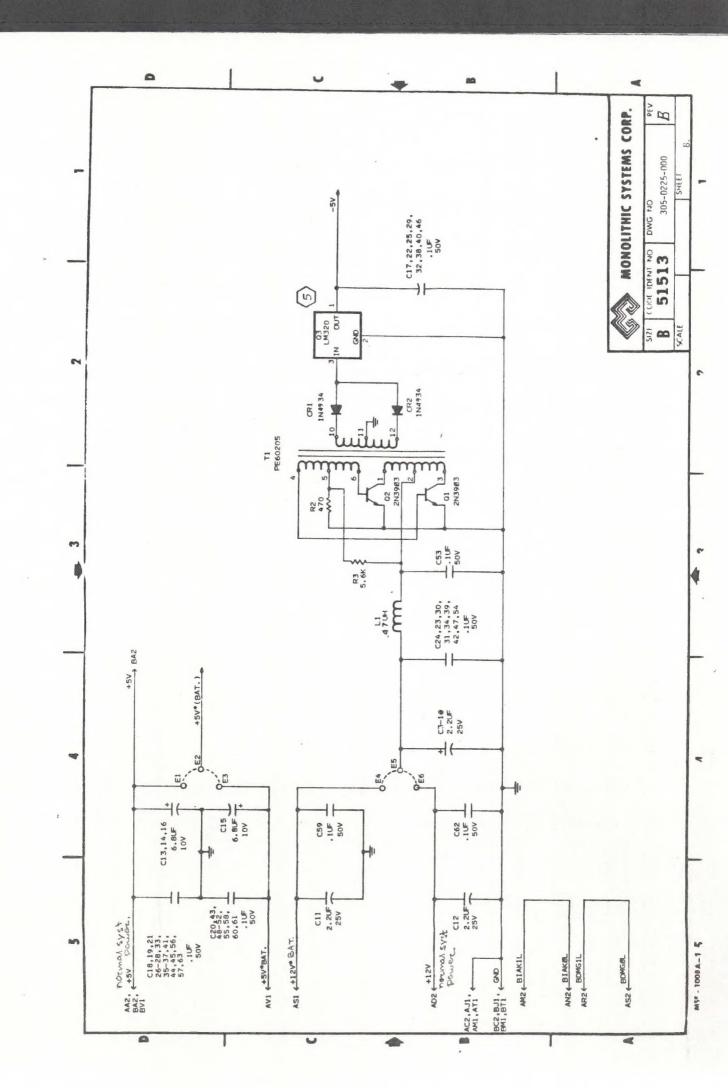












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U23,35		7 14			ю					
U28,36		7 14			4					
U22		7 14			20					
U30		7 14			9					
U29		7 14			7					T
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U39					6					1
U20,U21,U40		7 14			10					T
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74LS240 U7,U38		10 20			13					
		10 20			14					
74L5280 U16,U18		7 14			15					
74LS373 U4,5,6,9		10 20			16					T
74LS393 UIS		7 14			17					T
013		7 14			18					T
U34					19					T
137					20					
U31					21					T
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